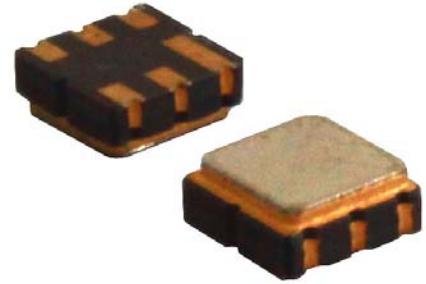


Application

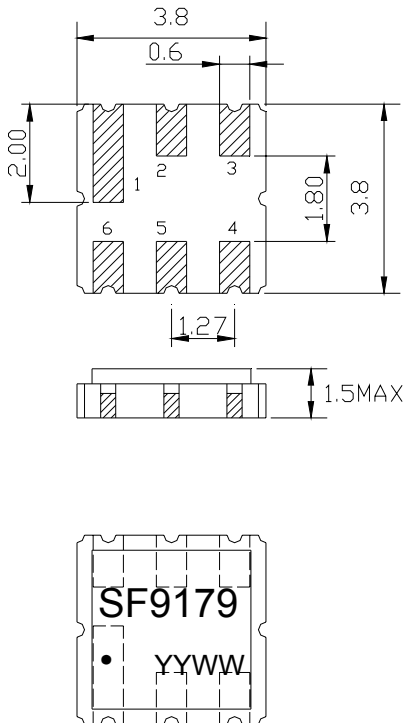
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 4 MHz



Features

- Ceramic Package for **Surface Mounted Technology (SMT)**
- **RoHS** compatible
- Package size 3.80x3.80x1.50mm³
- Package Code DCC6
- **Electrostatic Sensitive Device(ESD)**

Package Dimensions (Unit: mm)



Pin Configuration

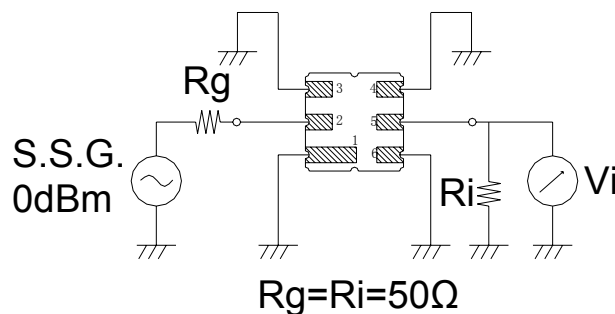
Pin No.	Description
2	Input
5	Output
1,3,4,6	Ground

Marking Description

S	Trademark
F	SAW Filter
9179	Part Number
●	Pin 1
YYWW	Year Code & Week Code

*Fig: If the products produced in 06th week of 2012,
The year code & week code is 1206.

Test Circuit



Performance**Maximum Rating**

Item		Value	Unit
DC Voltage	V _{DC}	3	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T _{stg}	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm

Electronic Characteristics

Test Temperature: 25°C±2°C

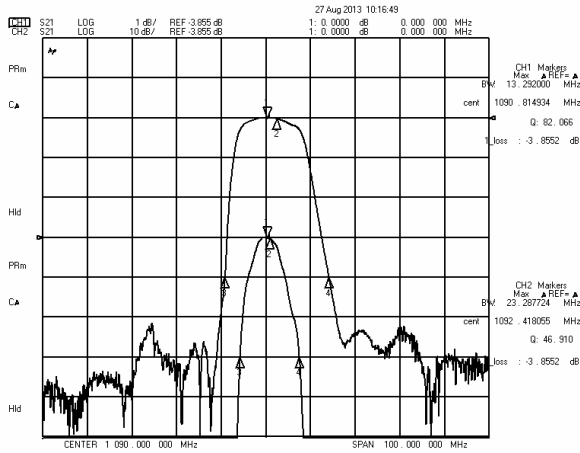
Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

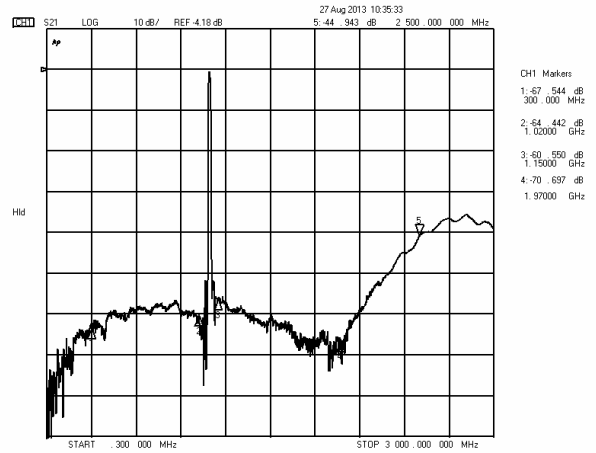
Item		Minimum	Typical	Maximum	Unit
Center Frequency	f _c		1090		MHz
Insertion Loss(min)	IL		4.0	6.0	dB
1dB BandWidth	BW _{-1dB}	4.0	8.0		MHz
3dB BandWidth	BW _{-3dB}		13.0	15.0	MHz
40dB BandWidth	BW _{-40dB}		23.0	30.0	MHz
Group Delay Ripple 1088.00– 1092.00MHz	GDR		15.0	30.0	ns
Absolute Attenuation	α				
DC - 300.00 MHz		50.0	55.0		dB
300.00 - 1020.00MHz		50.0	55.0		dB
1150.00 - 1970.00 MHz		50.0	55.0		dB
1970.00 - 2500.00 MHz		35.0	40.0		dB
2500.00 - 3000.00MHz		30.0	35.0		dB
Input VSWR 1088.00– 1092.00MHz			1.6:1	2.0:1	/
Output VSWR 1088.00– 1092.00MHz			1.6:1	2.0:1	/

Frequency Characteristics

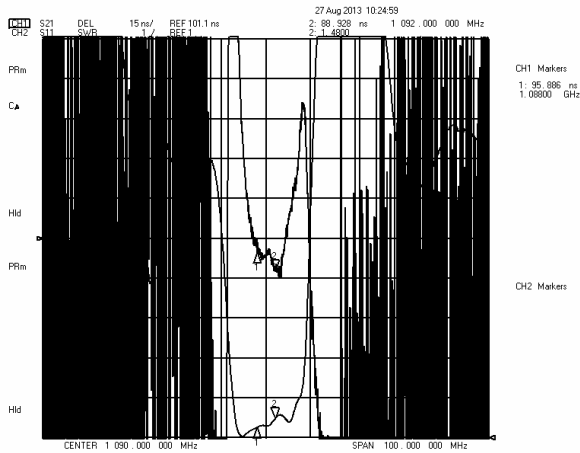
Frequency Response



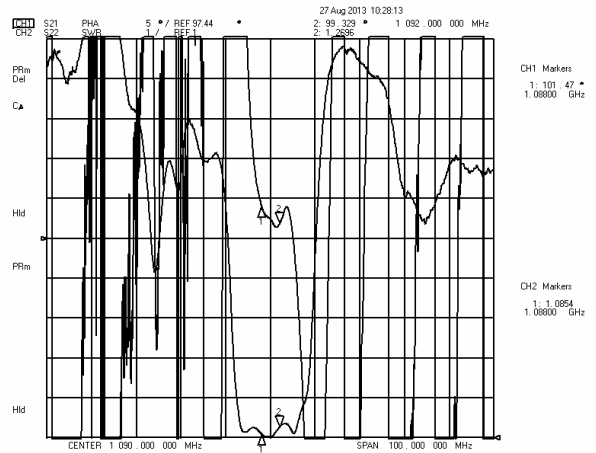
Frequency Response (wideband)



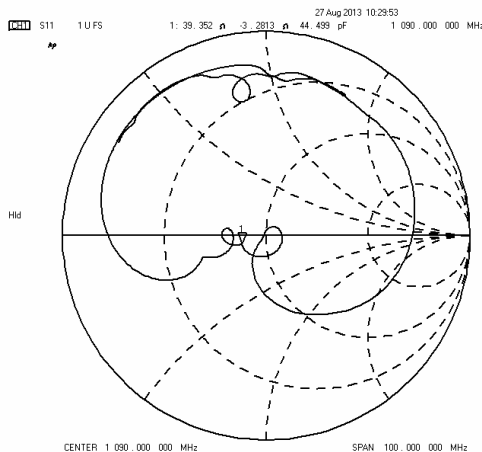
Delay Ripple & S11 VSWR



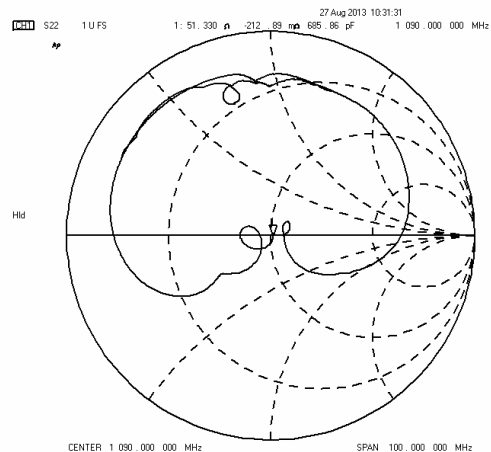
Phase Linearity & S22 VSWR



S11 Smith Chart

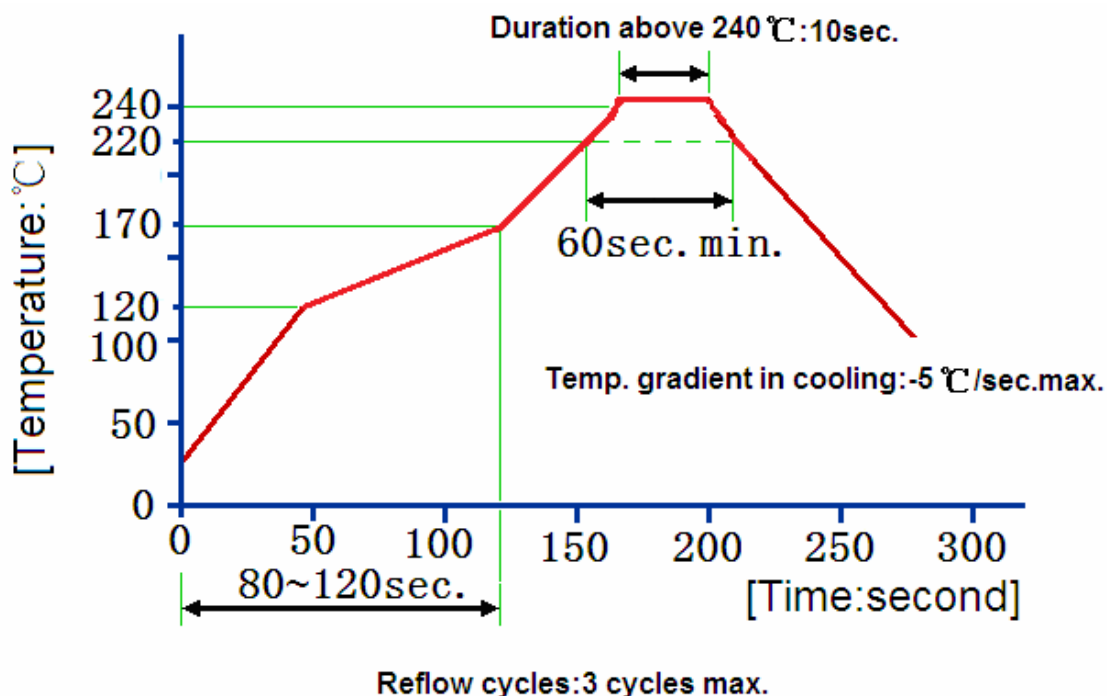


S22 Smith Chart



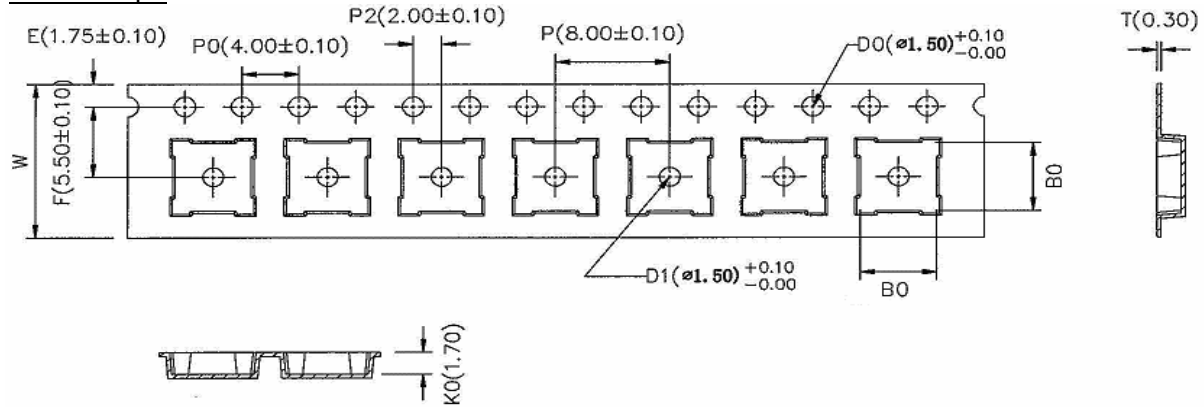
Reliability (The SAW components shall remain electrical performance after tests)

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: $85^{\circ}\text{C}\pm 2^{\circ}\text{C}$, Duration: 250h , Recovery time: $2\text{h}\pm 0.5\text{h}$ (2) Temperature: $-55^{\circ}\text{C}\pm 3^{\circ}\text{C}$, Duration: 250h ,Recovery time: $2\text{h}\pm 0.5\text{h}$
2	Humidity Test	Conditions: $60^{\circ}\text{C}\pm 2^{\circ}\text{C}$, 90~95% RH Duration: 250h
3	Thermal Shock	Heat cycle conditions: $\text{TA}=-55^{\circ}\text{C}\pm 3^{\circ}\text{C}$, $\text{TB}=85^{\circ}\text{C}\pm 2^{\circ}\text{C}$, $t_1=t_2=30\text{min}$, Switch time: $\leq 3\text{min}$, Cycle time: 100 times, Recovery time: $2\text{h}\pm 0.5\text{h}$.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude:1.5mm Directions: X,Y and Z Duration: 2h
5	Drop Test	Cycle time: 10 times Height: 1.0m
6	Solder Ability Test	Temperature: $245^{\circ}\text{C}\pm 5^{\circ}\text{C}$ Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5
7	Resistance to Soldering Heat	(1)Thickness of PCB:1mm , Solder condition: $260^{\circ}\text{C}\pm 5^{\circ}\text{C}$, Duration: $10\pm 1\text{s}$ (2)Temperature of Soldering Iron: $350^{\circ}\text{C}\pm 10^{\circ}\text{C}$, Duration: 3~4s, Recovery time : $2 \pm 0.5\text{h}$

Recommended Reflow Soldering Diagram

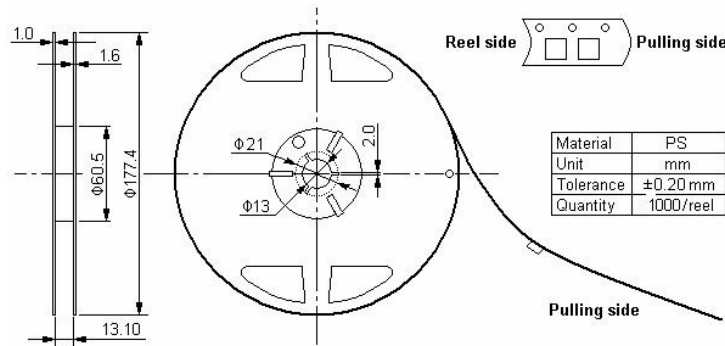
Packing Information

Carrier Tape



* B0: 5.35 for QCC8C; 4.15 for DCC6/QCC8B; 3.35 for DCC6C/QCC8D

Reel Dimensions



Outer Packing

Type	Quantity	Dimension	Description	Weight
Internal box	1000	190×188×42	carton box 2 reel / internal box	0.18
External box	10000	235×205×210		5 boxes / external box

Unit: mm

Unit: kg

Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.